

WHAT IS CLAIMED IS:

1. A semiconductor device comprising a pellet having a ground electrode, an outside signal terminal connected to the pellet, so as to receive signal which is likely to include noise; wherein

said outside signal terminal is surrounded with a ground terminal connected to said ground electrode in at least a half periphery.

2. A semiconductor device according to Claim 1, wherein said outside signal terminal can receive signal by antenna mounted on the apparatus where the semiconductor device is installed.

3. A semiconductor device according to Claim 1, wherein said outside signal terminal can receive operating clock from the apparatus where the semiconductor device is installed.

4. A semiconductor device according to Claim 1, wherein said outside signal terminal can receive electricity source from the apparatus where the semiconductor device is installed.

5. A semiconductor device according to Claim 1, wherein said ground terminal can surround only half of the periphery of said outside signal terminal.

6. A semiconductor device according to Claim 1, wherein said semiconductor device can be provided with fixing reinforcement terminal to reinforce the fixing of the semiconductor device to the apparatus installing it.

7. A semiconductor device according to Claim 1, wherein said semiconductor device is provided with plural terminals for electrical connection; and, each terminal is projecting at the base of semiconductor device to connect with a socket.

8. A semiconductor device according to Claim 1, wherein said semiconductor device is provided with a pair of semiconductor pellets; at the base of one of the semiconductor pellets, the other semiconductor pellet is located; and, electrodes of the other semiconductor pellet can be connected with the plural terminals electrically.

9. A semiconductor device according to Claim 1, wherein a pair of semiconductor pellets mentioned above are fixed with each other at confronting faces with conductive paste; and, this conductive paste can be electrically connected with said ground terminal.

10. A method for manufacturing semiconductor device, which comprises a pellet having a ground electrode, an outside signal terminal connected to the pellet, so as to receive signal likely to include noise, and plural terminals for inputting and outputting signals; and, is sealed in a resin as one body; wherein

said outside signal terminal is surrounded with a ground terminal connected to said ground electrode in at least a half periphery, having a peculiar form;

each ground terminal is exposed at the base of resin portion, after sealing each pellet located at the top of corresponding terminal in

the resin portion; and

each semiconductor device is formed by separating it from a wafer at mark of each ground terminal having peculiar form.

11. A method for manufacturing semiconductor device according to Claim 10, wherein

said pellet is located at a prescribed position with recognizing mark of the ground terminal.

12. A method for manufacturing semiconductor device according to Claim 10, wherein

each ground terminal exposed at the base of the resin portion is formed from one side of both surface of conductive board material, before locating said pellet.

13. A method for manufacturing semiconductor device according to Claim 12, wherein a buffer layer having same rate of expansion as the material of the apparatus to install the semiconductor device is formed at one side of the conductive board material, after forming said each terminal on said board material.

14. A method for manufacturing semiconductor device according to Claim 13, wherein each terminal is separated electrically by polishing said board material at the other face of board material until said buffer layer appears, after forming said buffer material.

15. A method for manufacturing semiconductor device according to

Claim 12, wherein a solder layer is formed at one face of the conductive board material, after forming said each terminal on said board material.

16. A method for manufacturing semiconductor device according to Claim 15, wherein each terminal is separated electrically by polishing said board material at the other face of the board material until said solder layer appears, after forming said solder layer.

17. A method for manufacturing semiconductor device according to Claim 16, wherein each connecting portion is formed with remaining solder with its surface tension at each terminal projecting at the base of said resin portion when said solder layer is melted to remove, after sealing the pellet in the resin.